

Technical data

Formats

min. board thickness:	0.1 mm (0.004")
max. board thickness:	6 mm (0.25")
min. board format:	250 x 350 mm (10" x 14")
max. board format:	610 x 610 mm (24" x 24")
Standard layout film formats:	660 x 660 (26" x 26"), 660 x 610 (26" x 24"), 660 x 508 (26" x 20")
Standard exposure formats:	610 x 610 (24"x24"), 640 x 580 (25,2" x 22,8), 622 x 477 (24,5" x 18,72)

Equipment data

Cooling (indirect water cooling):	
Water inflow HI:	with 8 - 12°C, 1"; 3.4 m³/h
Water inflow POC:	with 8 - 12°C, 3/4"; 1.6 m³/h
Cooling power HI:	16KW
Cooling power POC:	6.6KW
Allignment tollerance:	+/- 10 µm (0.0004")
Vacuum technology:	according to client specifications
Setting-up time:	<3 min
Dimensions (L x W x H)	2763 x 2182 x 1402 mm (HI) 2763 x 2074 x 1402 mm (POC)
Weight:	2000 Kg
Electrical connection HI:	400V, 50Hz, 24 KW, 3 phases, 63A
Options:	220V, 60Hz, 24 KW, 3 phases, 80A
Electrical connection POC:	400V, 50Hz, 20 KW, 3 phases, 50A
Options:	220V, 60Hz, 20 KW, 3 phases, 63A
Compressed-air supply:	6 bar, ca. 6 m³/h
Max. surface pressure:	18 N/cm²
Average ground load:	5000 N/m²
HI light source:	8 KW (6 KW option) air-cooled metal halogen lamp
POC light source:	3.5 KW (5 KW option) air-cooled metal halogen lamp
Illumination:	+/- 10%
HI intensity:	(60 - 80) mW/cm² (measuring device IL 390)
POC intensity:	(15 - 20) mW/cm² (measuring device IL 390)
Obtainable resolution (HI/POC):	Depends on the materials and preceeding and following processes
Layout film heating (HI/POC):	max. 2°C